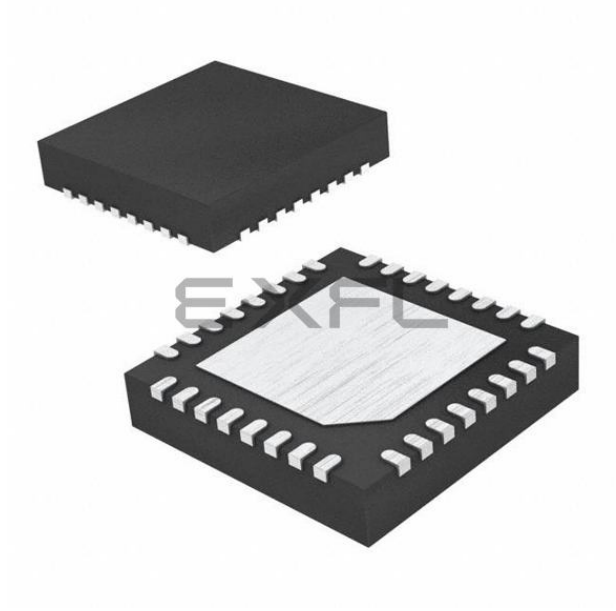

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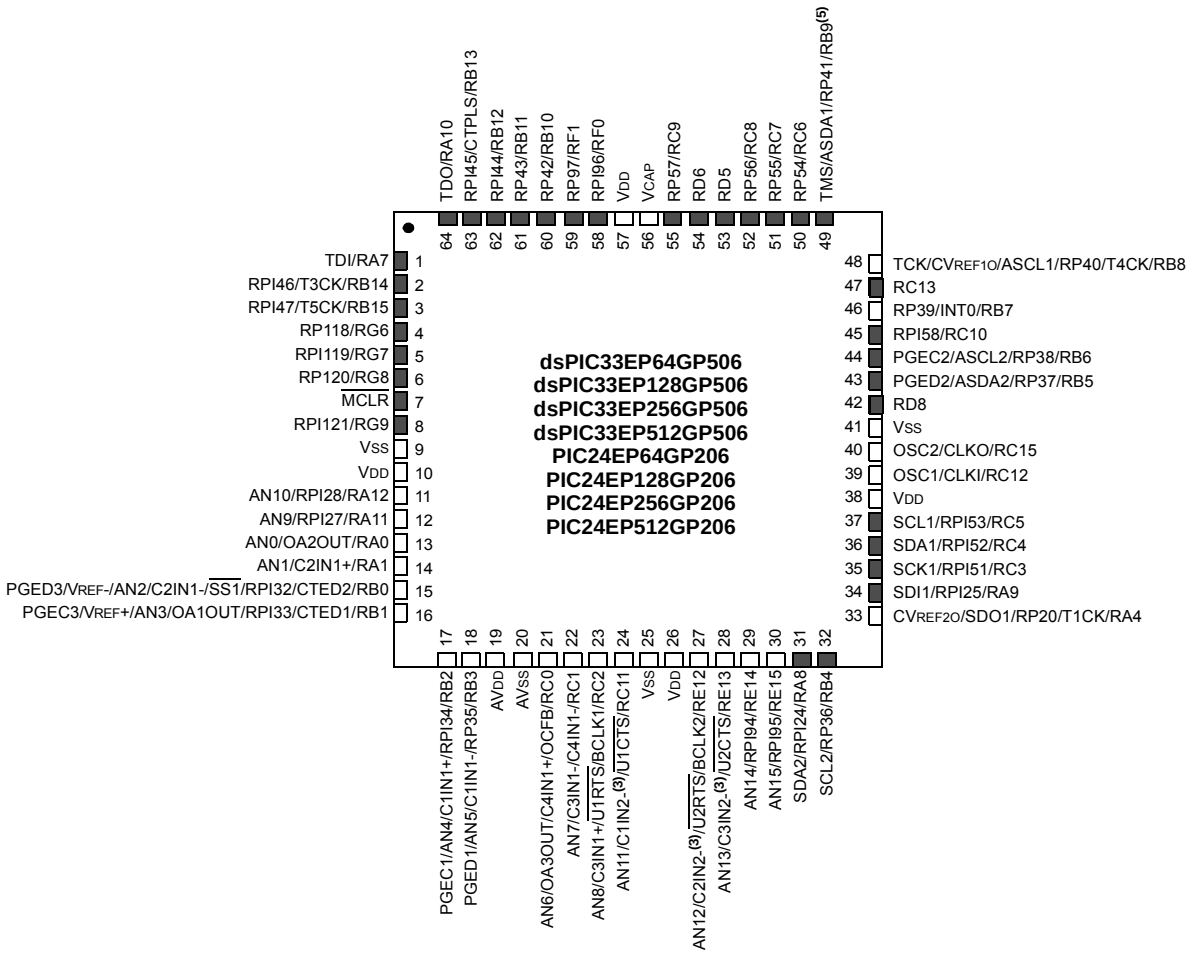
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	PIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24ep128mc202-e-mm

Pin Diagrams (Continued)

64-Pin QFN(1,2,3,4)

■ = Pins are up to 5V tolerant



Note 1: The RPn/RPIn pins can be used by any remappable peripheral with some limitation. See **Section 11.4 "Peripheral Pin Select (PPS)"** for available peripherals and for information on limitations.

2: Every I/O port pin (RAx-RGx) can be used as a Change Notification pin (CNAx-CNGx). See **Section 11.0 "I/O Ports"** for more information.

3: This pin is not available as an input when OPMODE (CMxCON<10>) = 1.

4: The metal pad at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

5: There is an internal pull-up resistor connected to the TMS pin when the JTAG interface is active. See the JTAGEN bit field in Table 27-2.

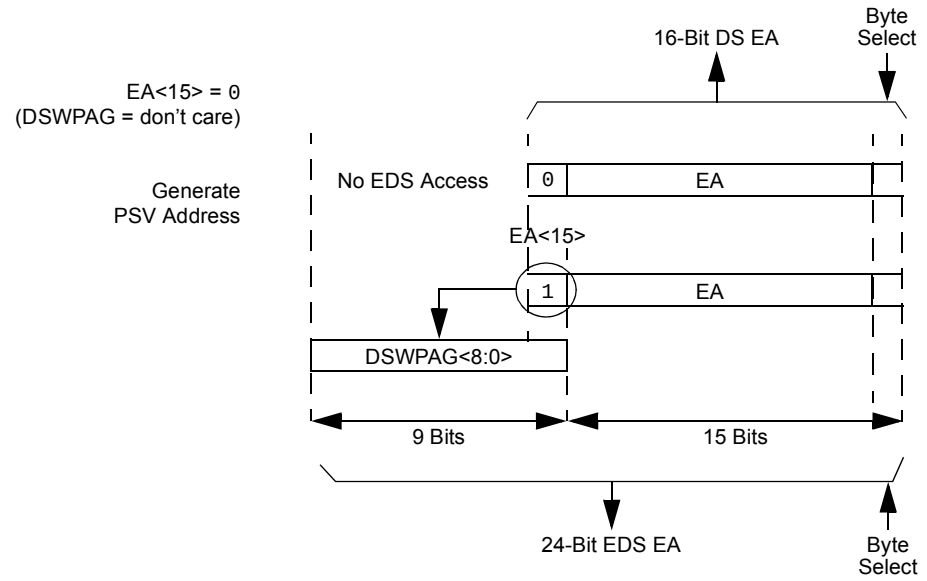
4.4 Special Function Register Maps

TABLE 4-1: CPU CORE REGISTER MAP FOR dsPIC33EPXXXMC20X/50X AND dsPIC33EPXXXGP50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
W0	0000	W0 (WREG)																xxxx
W1	0002	W1																xxxx
W2	0004	W2																xxxx
W3	0006	W3																xxxx
W4	0008	W4																xxxx
W5	000A	W5																xxxx
W6	000C	W6																xxxx
W7	000E	W7																xxxx
W8	0010	W8																xxxx
W9	0012	W9																xxxx
W10	0014	W10																xxxx
W11	0016	W11																xxxx
W12	0018	W12																xxxx
W13	001A	W13																xxxx
W14	001C	W14																xxxx
W15	001E	W15																xxxx
SPLIM	0020	SPLIM																0000
ACCAL	0022	ACCAL																0000
ACCAH	0024	ACCAH																0000
ACCAU	0026	Sign Extension of ACCA<39>								ACCAU								0000
ACCBL	0028	ACCBL																0000
ACCBH	002A	ACCBH																0000
ACCBU	002C	Sign Extension of ACCB<39>								ACCBU								0000
PCL	002E	PCL<15:0>															—	0000
PCH	0030	—	—	—	—	—	—	—	—	—	PCH<6:0>							0000
DSRPAG	0032	—	—	—	—	—	—	DSRPAG<9:0>										0001
DSWPAG	0034	—	—	—	—	—	—	—	DSWPAG<8:0>									0001
RCOUNT	0036	RCOUNT<15:0>																0000
DCOUNT	0038	DCOUNT<15:0>																0000
DOSTARTL	003A	DOSTARTL<15:1>															—	0000
DOSTARTH	003C	—	—	—	—	—	—	—	—	—	—	DOSTARTH<5:0>						0000
DOENDL	003E	DOENDL<15:1>															—	0000
DOENDH	0040	—	—	—	—	—	—	—	—	—	—	DOENDH<5:0>						0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

EXAMPLE 4-2: EXTENDED DATA SPACE (EDS) WRITE ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

The paged memory scheme provides access to multiple 32-Kbyte windows in the EDS and PSV memory. The Data Space Page registers, DSxPAG, in combination with the upper half of the Data Space address, can provide up to 16 Mbytes of additional address space in the EDS and 8 Mbytes (DSRPAG only) of PSV address space. The paged data memory space is shown in Example 4-3.

The Program Space (PS) can be accessed with a DSRPAG of 0x200 or greater. Only reads from PS are supported using the DSRPAG. Writes to PS are not supported, so DSWPAG is dedicated to DS, including EDS only. The Data Space and EDS can be read from, and written to, using DSRPAG and DSWPAG, respectively.

REGISTER 9-5: REFOCON: REFERENCE OSCILLATOR CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ROON	—	ROSSLP	ROSEL	RODIV3(1)	RODIV2(1)	RODIV1(1)	RODIV0(1)
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **ROON:** Reference Oscillator Output Enable bit
1 = Reference oscillator output is enabled on the REFCLK pin(2)
0 = Reference oscillator output is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **ROSSLP:** Reference Oscillator Run in Sleep bit
1 = Reference oscillator output continues to run in Sleep
0 = Reference oscillator output is disabled in Sleep

bit 12 **ROSEL:** Reference Oscillator Source Select bit
1 = Oscillator crystal is used as the reference clock
0 = System clock is used as the reference clock

bit 11-8 **RODIV<3:0>:** Reference Oscillator Divider bits(1)
1111 = Reference clock divided by 32,768
1110 = Reference clock divided by 16,384
1101 = Reference clock divided by 8,192
1100 = Reference clock divided by 4,096
1011 = Reference clock divided by 2,048
1010 = Reference clock divided by 1,024
1001 = Reference clock divided by 512
1000 = Reference clock divided by 256
0111 = Reference clock divided by 128
0110 = Reference clock divided by 64
0101 = Reference clock divided by 32
0100 = Reference clock divided by 16
0011 = Reference clock divided by 8
0010 = Reference clock divided by 4
0001 = Reference clock divided by 2
0000 = Reference clock

bit 7-0 **Unimplemented:** Read as '0'

Note 1: The reference oscillator output must be disabled (ROON = 0) before writing to these bits.
2: This pin is remappable. See **Section 11.4 "Peripheral Pin Select (PPS)"** for more information.

REGISTER 11-9: RPINR15: PERIPHERAL PIN SELECT INPUT REGISTER 15 (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X DEVICES ONLY)

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	HOME1R<6:0>						
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	INDX1R<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-8 **HOME1R<6:0>:** Assign QEI1 HOME1 (HOME1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

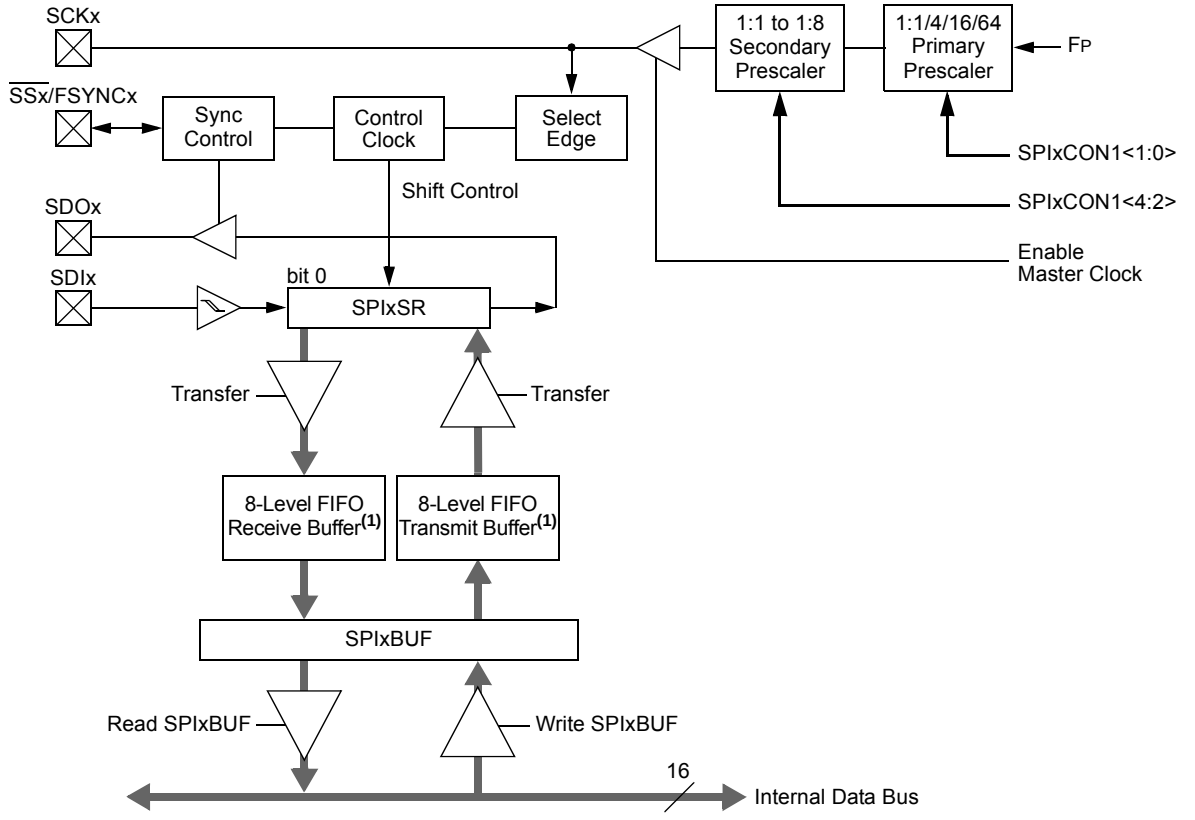
1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

bit 7 **Unimplemented:** Read as '0'

bit 6-0 **IND1XR<6:0>:** Assign QEI1 INDEX1 (INDX1) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

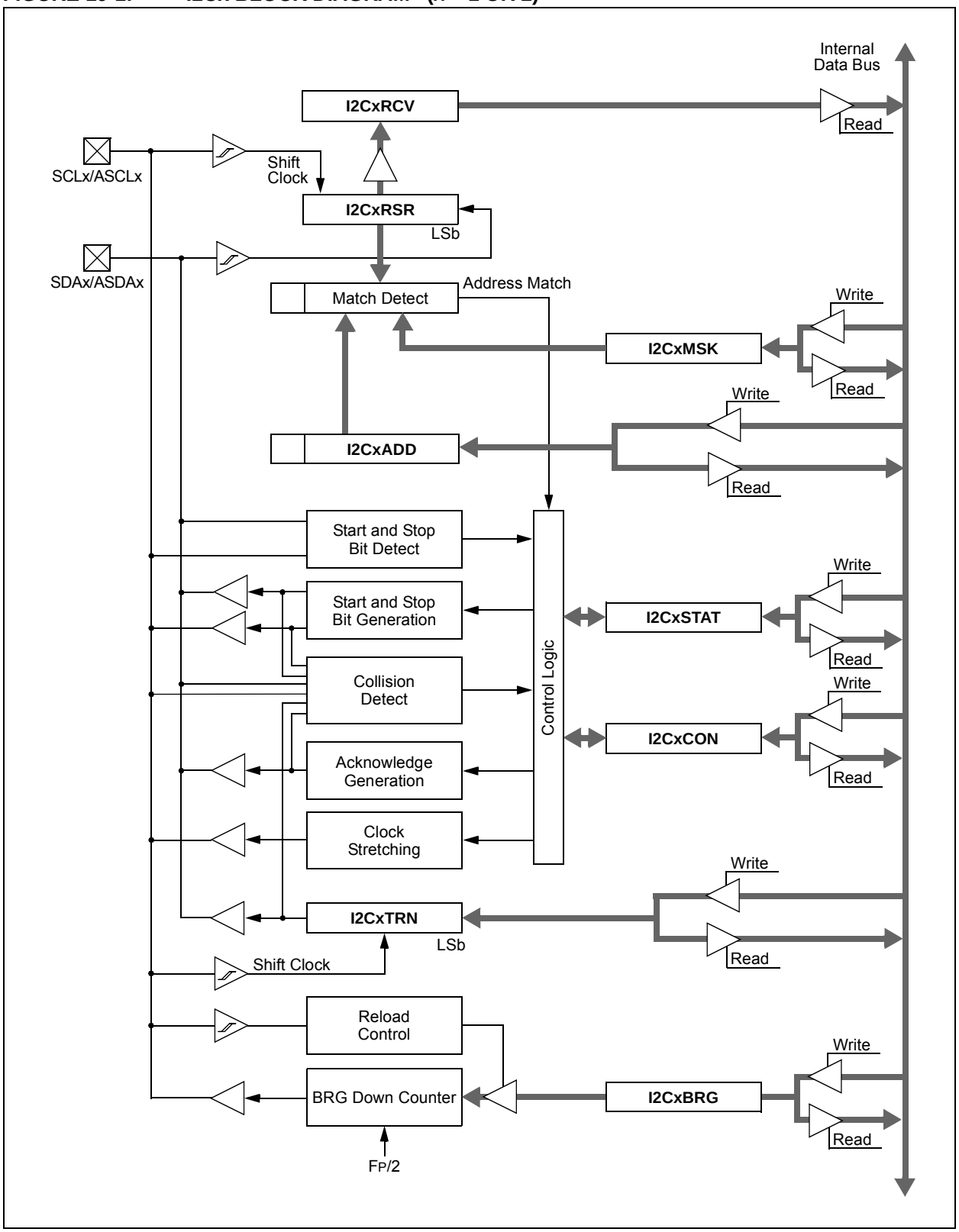
1111001 = Input tied to RPI121
.
.
.
0000001 = Input tied to CMP1
0000000 = Input tied to Vss

FIGURE 18-1: SPIx MODULE BLOCK DIAGRAM



Note 1: In Standard mode, the FIFO is only one level deep.

FIGURE 19-1: I2Cx BLOCK DIAGRAM (x = 1 OR 2)



19.2 I²C Control Registers

REGISTER 19-1: I2CxCON: I2Cx CONTROL REGISTER

R/W-0	U-0	R/W-0	R/W-1, HC	R/W-0	R/W-0	R/W-0	R/W-0
I2CEN	—	I2CSIDL	SCLREL	IPMIEN(1)	A10M	DISSLW	SMEN
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC	R/W-0, HC
GCEN	STREN	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN
bit 7							bit 0

Legend:	HC = Hardware Clearable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **I2CEN:** I2Cx Enable bit
1 = Enables the I2Cx module and configures the SDAx and SCLx pins as serial port pins
0 = Disables the I2Cx module; all I²C™ pins are controlled by port functions

bit 14 **Unimplemented:** Read as '0'

bit 13 **I2CSIDL:** I2Cx Stop in Idle Mode bit
1 = Discontinues module operation when device enters an Idle mode
0 = Continues module operation in Idle mode

bit 12 **SCLREL:** SCLx Release Control bit (when operating as I²C slave)
1 = Releases SCLx clock
0 = Holds SCLx clock low (clock stretch)
If STREN = 1:
Bit is R/W (i.e., software can write '0' to initiate stretch and write '1' to release clock). Hardware is clear at the beginning of every slave data byte transmission. Hardware is clear at the end of every slave address byte reception. Hardware is clear at the end of every slave data byte reception.
If STREN = 0:
Bit is R/S (i.e., software can only write '1' to release clock). Hardware is clear at the beginning of every slave data byte transmission. Hardware is clear at the end of every slave address byte reception.

bit 11 **IPMIEN:** Intelligent Peripheral Management Interface (IPMI) Enable bit(1)
1 = IPMI mode is enabled; all addresses are Acknowledged
0 = IPMI mode disabled

bit 10 **A10M:** 10-Bit Slave Address bit
1 = I2CxADD is a 10-bit slave address
0 = I2CxADD is a 7-bit slave address

bit 9 **DISSLW:** Disable Slew Rate Control bit
1 = Slew rate control is disabled
0 = Slew rate control is enabled

bit 8 **SMEN:** SMBus Input Levels bit
1 = Enables I/O pin thresholds compliant with SMBus specification
0 = Disables SMBus input thresholds

bit 7 **GCEN:** General Call Enable bit (when operating as I²C slave)
1 = Enables interrupt when a general call address is received in I2CxRSR (module is enabled for reception)
0 = General call address disabled

Note 1: When performing master operations, ensure that the IPMIEN bit is set to '0'.

REGISTER 21-22: CxRXFUL1: ECANx RECEIVE BUFFER FULL REGISTER 1

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL15	RXFUL14	RXFUL13	RXFUL12	RXFUL11	RXFUL10	RXFUL9	RXFUL8
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL7	RXFUL6	RXFUL5	RXFUL4	RXFUL3	RXFUL2	RXFUL1	RXFUL0
bit 7							bit 0

Legend:	C = Writable bit, but only ‘0’ can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL<15:0>:** Receive Buffer n Full bits
1 = Buffer is full (set by module)
0 = Buffer is empty (cleared by user software)

REGISTER 21-23: CxRXFUL2: ECANx RECEIVE BUFFER FULL REGISTER 2

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL31	RXFUL30	RXFUL29	RXFUL28	RXFUL27	RXFUL26	RXFUL25	RXFUL24
bit 15							bit 8

R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0	R/C-0
RXFUL23	RXFUL22	RXFUL21	RXFUL20	RXFUL19	RXFUL18	RXFUL17	RXFUL16
bit 7							bit 0

Legend:	C = Writable bit, but only ‘0’ can be written to clear the bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **RXFUL<31:16>:** Receive Buffer n Full bits
1 = Buffer is full (set by module)
0 = Buffer is empty (cleared by user software)

REGISTER 22-2: CTMUCON2: CTMU CONTROL REGISTER 2

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
EDG1MOD	EDG1POL	EDG1SEL3	EDG1SEL2	EDG1SEL1	EDG1SEL0	EDG2STAT	EDG1STAT
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0
EDG2MOD	EDG2POL	EDG2SEL3	EDG2SEL2	EDG2SEL1	EDG2SEL0	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **EDG1MOD:** Edge 1 Edge Sampling Mode Selection bit
1 = Edge 1 is edge-sensitive
0 = Edge 1 is level-sensitive

bit 14 **EDG1POL:** Edge 1 Polarity Select bit
1 = Edge 1 is programmed for a positive edge response
0 = Edge 1 is programmed for a negative edge response

bit 13-10 **EDG1SEL<3:0>:** Edge 1 Source Select bits
1xxx = Reserved
01xx = Reserved
0011 = CTED1 pin
0010 = CTED2 pin
0001 = OC1 module
0000 = Timer1 module

bit 9 **EDG2STAT:** Edge 2 Status bit
Indicates the status of Edge 2 and can be written to control the edge source.
1 = Edge 2 has occurred
0 = Edge 2 has not occurred

bit 8 **EDG1STAT:** Edge 1 Status bit
Indicates the status of Edge 1 and can be written to control the edge source.
1 = Edge 1 has occurred
0 = Edge 1 has not occurred

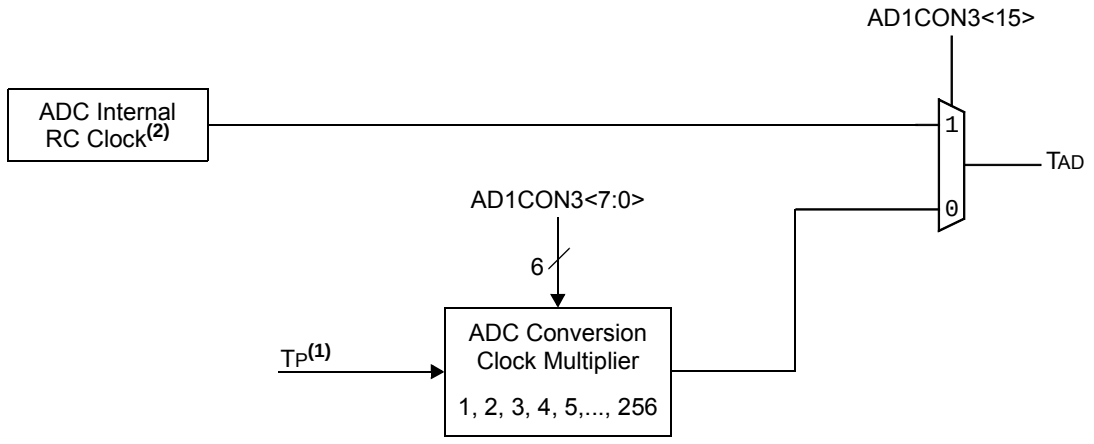
bit 7 **EDG2MOD:** Edge 2 Edge Sampling Mode Selection bit
1 = Edge 2 is edge-sensitive
0 = Edge 2 is level-sensitive

bit 6 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge 2 is programmed for a positive edge response
0 = Edge 2 is programmed for a negative edge response

bit 5-2 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = Reserved
01xx = Reserved
0100 = CMP1 module
0011 = CTED2 pin
0010 = CTED1 pin
0001 = OC1 module
0000 = IC1 module

bit 1-0 **Unimplemented:** Read as '0'

FIGURE 23-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



Note 1: TP = 1/FP.

2: See the ADC electrical specifications in **Section 30.0 "Electrical Characteristics"** for the exact RC clock value.

REGISTER 25-7: CVRCON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER

U-0	R/W-0	U-0	U-0	U-0	R/W-0	U-0	U-0
—	CVR2OE(1)	—	—	—	VREFSEL	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CVREN	CVR1OE(1)	CVRR	CVRSS(2)	CVR3	CVR2	CVR1	CVR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14 **CVR2OE:** Comparator Voltage Reference 2 Output Enable bit(1)
1 = (AVDD – AVSS)/2 is connected to the CVREF2O pin
0 = (AVDD – AVSS)/2 is disconnected from the CVREF2O pin

bit 13-11 **Unimplemented:** Read as '0'

bit 10 **VREFSEL:** Comparator Voltage Reference Select bit
1 = CVREFIN = VREF+
0 = CVREFIN is generated by the resistor network

bit 9-8 **Unimplemented:** Read as '0'

bit 7 **CVREN:** Comparator Voltage Reference Enable bit
1 = Comparator voltage reference circuit is powered on
0 = Comparator voltage reference circuit is powered down

bit 6 **CVR1OE:** Comparator Voltage Reference 1 Output Enable bit(1)
1 = Voltage level is output on the CVREF1O pin
0 = Voltage level is disconnected from then CVREF1O pin

bit 5 **CVRR:** Comparator Voltage Reference Range Selection bit
1 = CVRSRC/24 step-size
0 = CVRSRC/32 step-size

bit 4 **CVRSS:** Comparator Voltage Reference Source Selection bit(2)
1 = Comparator voltage reference source, CVRSRC = (VREF+) – (AVSS)
0 = Comparator voltage reference source, CVRSRC = AVDD – AVSS

bit 3-0 **CVR<3:0>** Comparator Voltage Reference Value Selection 0 ≤ CVR<3:0> ≤ 15 bits
When CVRR = 1:
CVREFIN = (CVR<3:0>/24) • (CVRSRC)
When CVRR = 0:
CVREFIN = (CVRSRC/4) + (CVR<3:0>/32) • (CVRSRC)

Note 1: CVRxOE overrides the TRISx and the ANSELx bit settings.
2: In order to operate with CVRSS = 1, at least one of the comparator modules must be enabled.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax	Description	# of Words	# of Cycles(2)	Status Flags Affected
46	MOV	MOV f,Wn	Move f to Wn	1	1	None
		MOV f	Move f to f	1	1	None
		MOV f,WREG	Move f to WREG	1	1	None
		MOV #lit16,Wn	Move 16-bit literal to Wn	1	1	None
		MOV.b #lit8,Wn	Move 8-bit literal to Wn	1	1	None
		MOV Wn,f	Move Wn to f	1	1	None
		MOV Wso,Wdo	Move Ws to Wd	1	1	None
		MOV WREG,f	Move WREG to f	1	1	None
		MOV.D Wns,Wd	Move Double from W(ns):W(ns + 1) to Wd	1	2	None
		MOV.D Ws,Wnd	Move Double from Ws to W(nd + 1):W(nd)	1	2	None
47	MOVPAG	MOVPAG #lit10,DSRPAG	Move 10-bit literal to DSRPAG	1	1	None
		MOVPAG #lit9,DSWPAG	Move 9-bit literal to DSWPAG	1	1	None
		MOVPAG #lit8,TBLPAG	Move 8-bit literal to TBLPAG	1	1	None
		MOVPAG Ws, DSRPAG	Move Ws<9:0> to DSRPAG	1	1	None
		MOVPAG Ws, DSWPAG	Move Ws<8:0> to DSWPAG	1	1	None
		MOVPAG Ws, TBLPAG	Move Ws<7:0> to TBLPAG	1	1	None
48	MOVSAC	MOVSAC Acc,Wx,Wxd,Wy,Wyd,AWB(1)	Prefetch and store accumulator	1	1	None
49	MPY	MPY Wm*Wn,Acc,Wx,Wxd,Wy,Wyd(1)	Multiply Wm by Wn to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		MPY Wm*Wm,Acc,Wx,Wxd,Wy,Wyd(1)	Square Wm to Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
50	MPY.N	MPY.N Wm*Wn,Acc,Wx,Wxd,Wy,Wyd(1)	-(Multiply Wm by Wn) to Accumulator	1	1	None
51	MSC	MSC Wm*Wm,Acc,Wx,Wxd,Wy,Wyd,AWB(1)	Multiply and Subtract from Accumulator	1	1	OA,OB,OAB, SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.
2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 28-2: INSTRUCTION SET OVERVIEW (CONTINUED)

Base Instr #	Assembly Mnemonic	Assembly Syntax		Description	# of Words	# of Cycles(2)	Status Flags Affected
53	NEG	NEG	Acc(1)	Negate Accumulator	1	1	OA,OB,OAB, SA,SB,SAB
		NEG	f	f = $\bar{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG	f,WREG	WREG = $\bar{f}$ + 1	1	1	C,DC,N,OV,Z
		NEG	Ws,Wd	Wd = $\overline{Ws}$ + 1	1	1	C,DC,N,OV,Z
54	NOP	NOP		No Operation	1	1	None
		NOPR		No Operation	1	1	None
55	POP	POP	f	Pop f from Top-of-Stack (TOS)	1	1	None
		POP	Wdo	Pop from Top-of-Stack (TOS) to Wdo	1	1	None
		POP.D	Wnd	Pop from Top-of-Stack (TOS) to W(nd):W(nd + 1)	1	2	None
		POP.S		Pop Shadow Registers	1	1	All
56	PUSH	PUSH	f	Push f to Top-of-Stack (TOS)	1	1	None
		PUSH	Wso	Push Wso to Top-of-Stack (TOS)	1	1	None
		PUSH.D	Wns	Push W(ns):W(ns + 1) to Top-of-Stack (TOS)	1	2	None
		PUSH.S		Push Shadow Registers	1	1	None
57	PWRSAV	PWRSAV	#lit1	Go into Sleep or Idle mode	1	1	WDTO,Sleep
58	RCALL	RCALL	Expr	Relative Call	1	4	SFA
		RCALL	Wn	Computed Call	1	4	SFA
59	REPEAT	REPEAT	#lit15	Repeat Next Instruction lit15 + 1 times	1	1	None
		REPEAT	Wn	Repeat Next Instruction (Wn) + 1 times	1	1	None
60	RESET	RESET		Software device Reset	1	1	None
61	RETFIE	RETFIE		Return from interrupt	1	6 (5)	SFA
62	RETLW	RETLW	#lit10,Wn	Return with literal in Wn	1	6 (5)	SFA
63	RETURN	RETURN		Return from Subroutine	1	6 (5)	SFA
64	RLC	RLC	f	f = Rotate Left through Carry f	1	1	C,N,Z
		RLC	f,WREG	WREG = Rotate Left through Carry f	1	1	C,N,Z
		RLC	Ws,Wd	Wd = Rotate Left through Carry Ws	1	1	C,N,Z
65	RLNC	RLNC	f	f = Rotate Left (No Carry) f	1	1	N,Z
		RLNC	f,WREG	WREG = Rotate Left (No Carry) f	1	1	N,Z
		RLNC	Ws,Wd	Wd = Rotate Left (No Carry) Ws	1	1	N,Z
66	RRC	RRC	f	f = Rotate Right through Carry f	1	1	C,N,Z
		RRC	f,WREG	WREG = Rotate Right through Carry f	1	1	C,N,Z
		RRC	Ws,Wd	Wd = Rotate Right through Carry Ws	1	1	C,N,Z
67	RRNC	RRNC	f	f = Rotate Right (No Carry) f	1	1	N,Z
		RRNC	f,WREG	WREG = Rotate Right (No Carry) f	1	1	N,Z
		RRNC	Ws,Wd	Wd = Rotate Right (No Carry) Ws	1	1	N,Z
68	SAC	SAC	Acc,#Slit4,Wdo(1)	Store Accumulator	1	1	None
		SAC.R	Acc,#Slit4,Wdo(1)	Store Rounded Accumulator	1	1	None
69	SE	SE	Ws,Wnd	Wnd = sign-extended Ws	1	1	C,N,Z
70	SETM	SETM	f	f = 0xFFFF	1	1	None
		SETM	WREG	WREG = 0xFFFF	1	1	None
		SETM	Ws	Ws = 0xFFFF	1	1	None
71	SFTAC	SFTAC	Acc,Wn(1)	Arithmetic Shift Accumulator by (Wn)	1	1	OA,OB,OAB, SA,SB,SAB
		SFTAC	Acc,#Slit6(1)	Arithmetic Shift Accumulator by Slit6	1	1	OA,OB,OAB, SA,SB,SAB

Note 1: These instructions are available in dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

2: Read and Read-Modify-Write (e.g., bit operations and logical operations) on non-CPU SFRs incur an additional instruction cycle.

TABLE 30-11: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
DI60a	IICL	**Input Low Injection Current**	0	—	-5(4,7)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP and RB7
DI60b	IICH	**Input High Injection Current**	0	—	+5(5,6,7)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, RB7 and all 5V tolerant pins(6)
DI60c	∑IICT	**Total Input Injection Current (sum of all I/O and control pins)**	-20(8)	—	+20(8)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL + | IICH |) ≤ ∑IICT

Note 1: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current can be measured at different input voltages.

2: Negative current is defined as current sourced by the pin.

3: See the **"Pin Diagrams"** section for the 5V tolerant I/O pins.

4: VIL source < (VSS – 0.3). Characterized but not tested.

5: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

6: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

7: Non-zero injection currents can affect the ADC results by approximately 4-6 counts.

8: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 30-54: OP AMP/COMPARATOR VOLTAGE REFERENCE SETTLING TIME SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 2): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
VR310	TSET	Settling Time	—	1	10	μs	**(Note 1)**

Note 1: Settling time is measured while CVRR = 1 and CVR<3:0> bits transition from '0000' to '1111'.

2: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

TABLE 30-55: OP AMP/COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

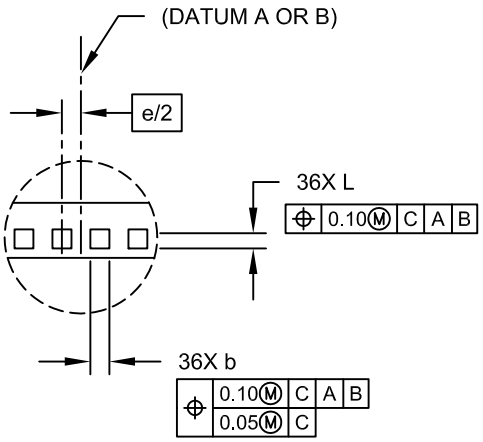
DC CHARACTERISTICS			Standard Operating Conditions (see Note 1): 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
VRD310	CVRES	Resolution	CVRSRC/24	—	CVRSRC/32	LSb	
VRD311	CVRAA	Absolute Accuracy(2)	—	±25	—	mV	CVRSRC = 3.3V
VRD313	CVRSRC	Input Reference Voltage	0	—	AVDD + 0.3	V	
VRD314	CVROUT	Buffer Output Resistance(2)	—	1.5k	—	Ω	

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

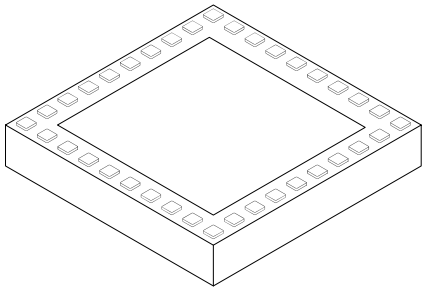
2: Parameter is characterized but not tested in manufacturing.

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A



Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX
Number of Pins	N		36	
Number of Pins per Side	ND		10	
Number of Pins per Side	NE		8	
Pitch	e		0.50 BSC	
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.025	-	0.075
Overall Width	E		5.00 BSC	
Exposed Pad Width	E2	3.60	3.75	3.90
Overall Length	D		5.00 BSC	
Exposed Pad Length	D2	3.60	3.75	3.90
Contact Width	b	0.20	0.25	0.30
Contact Length	L	0.20	0.25	0.30
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

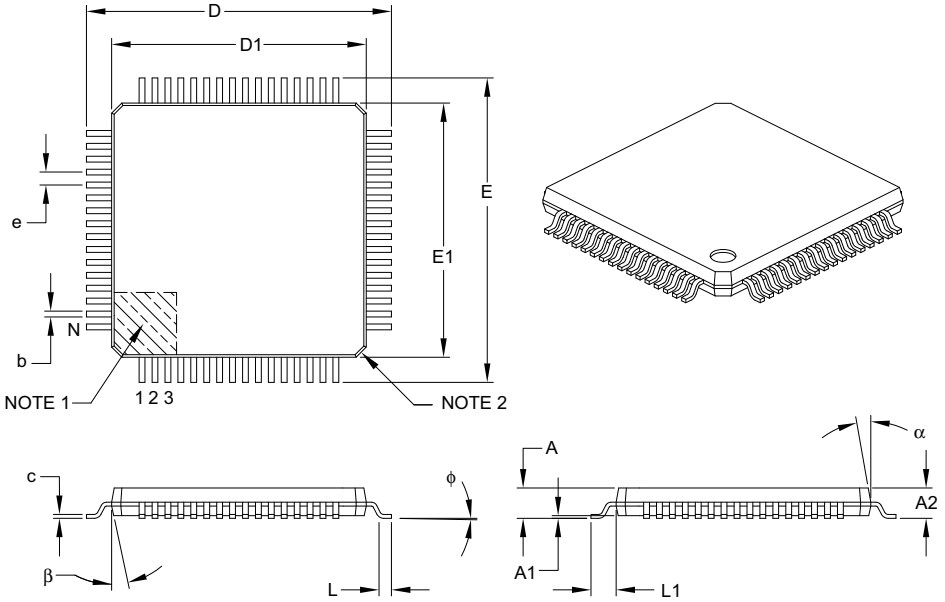
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-187C Sheet 2 of 2

64-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	φ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085B

TABLE A-2: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 16.0 "High-Speed PWM Module (dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X Devices Only)"	Updated the High-Speed PWM Module Register Interconnection Diagram (see Figure 16-2). Added the TRGCONx and TRIGx registers (see Register 16-12 and Register 16-14, respectively).
Section 21.0 "Enhanced CAN (ECAN™) Module (dsPIC33EPXXXGP/MC50X Devices Only)"	Updated the CANCKS bit value definitions in CiCTRL1: ECAN Control Register 1 (see Register 21-1).
Section 22.0 "Charge Time Measurement Unit (CTMU)"	Updated the IRNG<1:0> bit value definitions and added Note 2 in the CTMU Current Control Register (see Register 22-3).
Section 25.0 "Op amp/ Comparator Module"	Updated the Op amp/Comparator I/O Operating Modes Diagram (see Figure 25-1). Updated the User-programmable Blanking Function Block Diagram (see Figure 25-3). Updated the Digital Filter Interconnect Block Diagram (see Figure 25-4). Added **Section 25.1 "Op amp Application Considerations"**. Added Note 2 to the Comparator Control Register (see Register 25-2). Updated the bit definitions in the Comparator Mask Gating Control Register (see Register 25-5).
Section 27.0 "Special Features"	Updated the FICD Configuration Register, updated Note 1, and added Note 3 in the Configuration Byte Register Map (see Table 27-1). Added **Section 27.2 "User ID Words"**.
Section 30.0 "Electrical Characteristics"	Updated the following Absolute Maximum Ratings: • Maximum current out of V_{SS} pin • Maximum current into V_{DD} pin Added Note 1 to the Operating MIPS vs. Voltage (see Table 30-1). Updated all Idle Current (I_{IDLE}) Typical and Maximum DC Characteristics values (see Table 30-7). Updated all Doze Current (I_{DOZE}) Typical and Maximum DC Characteristics values (see Table 30-9). Added Note 2, removed Parameter CM24, updated the Typical values Parameters CM10, CM20, CM21, CM32, CM41, CM44, and CM45, and updated the Minimum values for CM40 and CM41, and the Maximum value for CM40 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14). Updated Note 2 and the Typical value for Parameter VR310 in the Op amp/ Comparator Reference Voltage Settling Time Specifications (see Table 30-15). Added Note 1, removed Parameter VRD312, and added Parameter VRD314 to the Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16). Updated the Minimum, Typical, and Maximum values for Internal LPRC Accuracy (see Table 30-22). Updated the Minimum, Typical, and Maximum values for Parameter SY37 in the Reset, Watchdog Timer, Oscillator Start-up Timer, Power-up Timer Timing Requirements (see Table 30-24). The Maximum Data Rate values were updated for the SPI2 Maximum Data/Clock Rate Summary (see Table 30-35)

NOTES: